

What is claimed is:

1. A method for manufacturing a multilayer ceramic electronic component, comprising the steps of:

preparing an unsintered multilayer ceramic body including stacked ceramic layers and internal electrodes, the internal electrodes being made mainly of a base metal;

removing organic materials from the unsintered multilayer ceramic body to provide a binder-removed multilayer ceramic body; and

sintering the binder-removed multilayer ceramic body under a reductive atmosphere,

wherein the amount of the organic materials remaining in the binder-removed multilayer ceramic body ranges from about 0.5 weight% to about 8.5 weight% of the binder-removed multilayer ceramic body.

2. The method of claim 1, wherein the removing step is performed under an inert, a neutral or a reductive gaseous atmosphere.

3. The method of claim 2, wherein the atmosphere includes H₂ or N₂.

4. The method of claim 1, wherein the removing step is performed under a pressure higher than 1 atmosphere.

5. The method of claim 1, wherein the amount of the organic materials remaining in

the binder-removed multilayer ceramic body ranges from about 1.0 weight% to about 5.0 weight% of the binder-removed multilayer ceramic body.

6. The method of claim 5, wherein the removing step is performed under an inert, a neutral or a reductive gaseous atmosphere.

7. The method of claim 6, wherein the atmosphere includes H₂ or N₂.

8. The method of claim 5, wherein the removing step is performed under a pressure higher than 1 atmosphere.

9. The method of claim 1, wherein the removal of the organic materials from the internal electrodes starts at a temperature higher than that employed for the removal of the organic materials from the ceramic layers in order to remove the organic materials uniformly throughout the unsintered multilayer ceramic body.

10. The method of claim 9, wherein the removal of the organic materials from the internal electrodes starts at a temperature higher than that employed for the removal of the organic materials from the ceramic layers by more than about 5°C.

11. The method of claim 10, wherein the removal of the organic materials from the internal electrodes starts at a temperature higher than that employed for the removal of

the organic materials from the ceramic layers by more than about 10°C.

12. The method of claim 1, wherein a vessel having meshes smaller than the size of the unsintered multilayer ceramic body is used for accommodating the unsintered multiplayer ceramic body during the removing step.

13. The method of claim 1, wherein the removing step includes the steps of increasing a pressure in a binder removing furnace up to a peak pressure, increasing a temperature in the binder removing furnace up to a peak temperature, decreasing the pressure when the temperature reaches a pressure-decreasing temperature, which is lower than the peak temperature, and maintaining the peak temperature for a predetermined of period.

14. The method of claim 13, wherein the peak pressure is about 10 atmospheres.

15. The method of claim 13, wherein the pressure-decreasing temperature is about 200°C and the peak temperature is about 300°C.

16. The method of claim 1, wherein the removal of the organic materials is performed by pyrolysis.